

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	512	257/738.ccls.	USPAT
2	BRS	L2	583	257/751.ccls.	USPAT
3	BRS	L3	157	257/751.ccls.	EPO; JPO; IBM TDB
4	BRS	L4	128	257/778.ccls.	EPO; JPO; IBM TDB
5	BRS	L5	51	257/738.ccls.	EPO; JPO; IBM TDB

	Type	Hits	Search Text	DBs
1	BRS	0	(bonding adj pad) and (ball or bump) and via and plug and passivation	EPO; JPO; IBM TDB
2	BRS	0	solder adj (ball or bump) and via and plug and passivation	EPO; JPO; IBM TDB
3	BRS	8	(bonding adj pad) and (ball or bump) and via and plug and passivation	USPAT
4	BRS	48	solder adj (ball or bump) and via and plug and passivation	USPAT
5	BRS	808	257/778.ccls.	USPAT
6	BRS	7	257/778.ccls. and (solder adj ball) and plug	USPAT